Title (en)

METHOD FOR PRODUCING ELECTRONIC COMPONENTS BY MEANS OF 3D PRINTING

Title (de)

VERFAHREN ZUR HERSTELLUNG VON ELEKTRONISCHEN BAUTEILEN MITTELS 3D-DRUCK

Title (fr)

PROCÉDÉ DE FABRICATION DE COMPOSANTS ÉLECTRONIQUES PAR IMPRESSION 3D

Publication

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Application

EP 17764368 A 20170904

Priority

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Abstract (en)

[origin: CA3031862A1] The present invention relates to a method for producing electronic components, in particular anodes, from valve metal powder by means of 3D printing and to the use of a valve metal powder for the production of electronic components by means of 3D printing. The present invention further relates to an anode which can be obtained by the method according to the invention as well as to a capacitor which comprises the anode according to the invention.

IPC 8 full level

H01G 9/052 (2006.01); **B33Y 80/00** (2015.01)

CPC (source: EP IL KR US)

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